Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

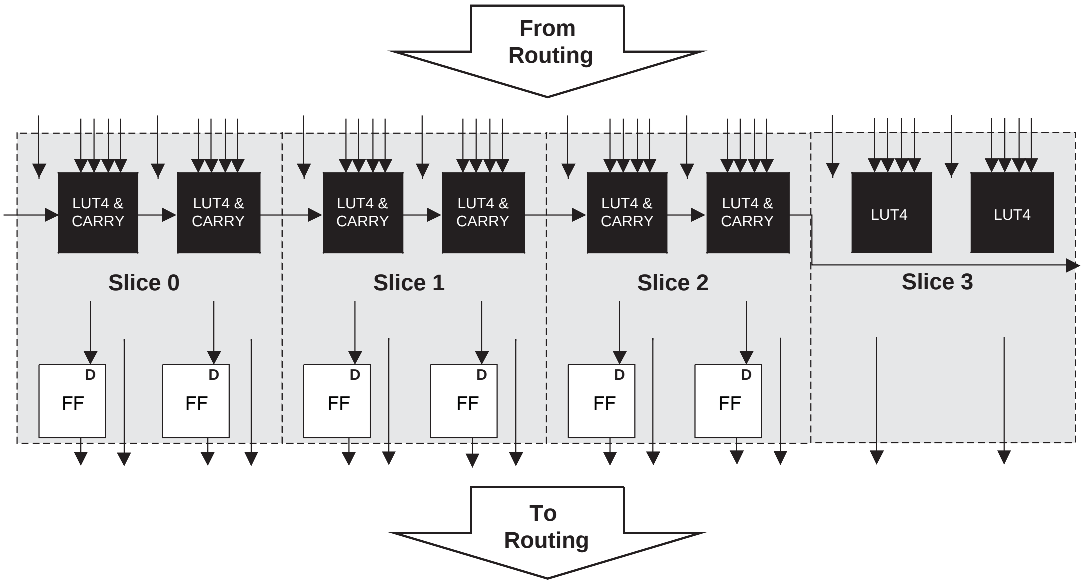
Details	
Product Status	Obsolete
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	48000
Total RAM Bits	4246528
Number of I/O	372
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FPBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m50e-6f672i

PFU Blocks

The core of the LatticeECP2/M device consists of PFU blocks, which are provided in two forms, the PFU and PFF. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of this data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-3. All the interconnections to and from PFU blocks are from routing. There are 50 inputs and 23 outputs associated with each PFU block.

Figure 2-3. PFU Diagram



Slice

Slice 0 through Slice 2 contain two LUT4s feeding two registers, whereas Slice 3 contains two LUT4s only. For PFUs, Slice 0 and Slice 2 can also be configured as distributed memory, a capability not available in the PFF. Table 2-1 shows the capability of the slices in both PFF and PFU blocks along with the operation modes they enable. In addition, each PFU contains some logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-4 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge triggered or level sensitive clocks.

Table 2-1. Resources and Modes Available per Slice

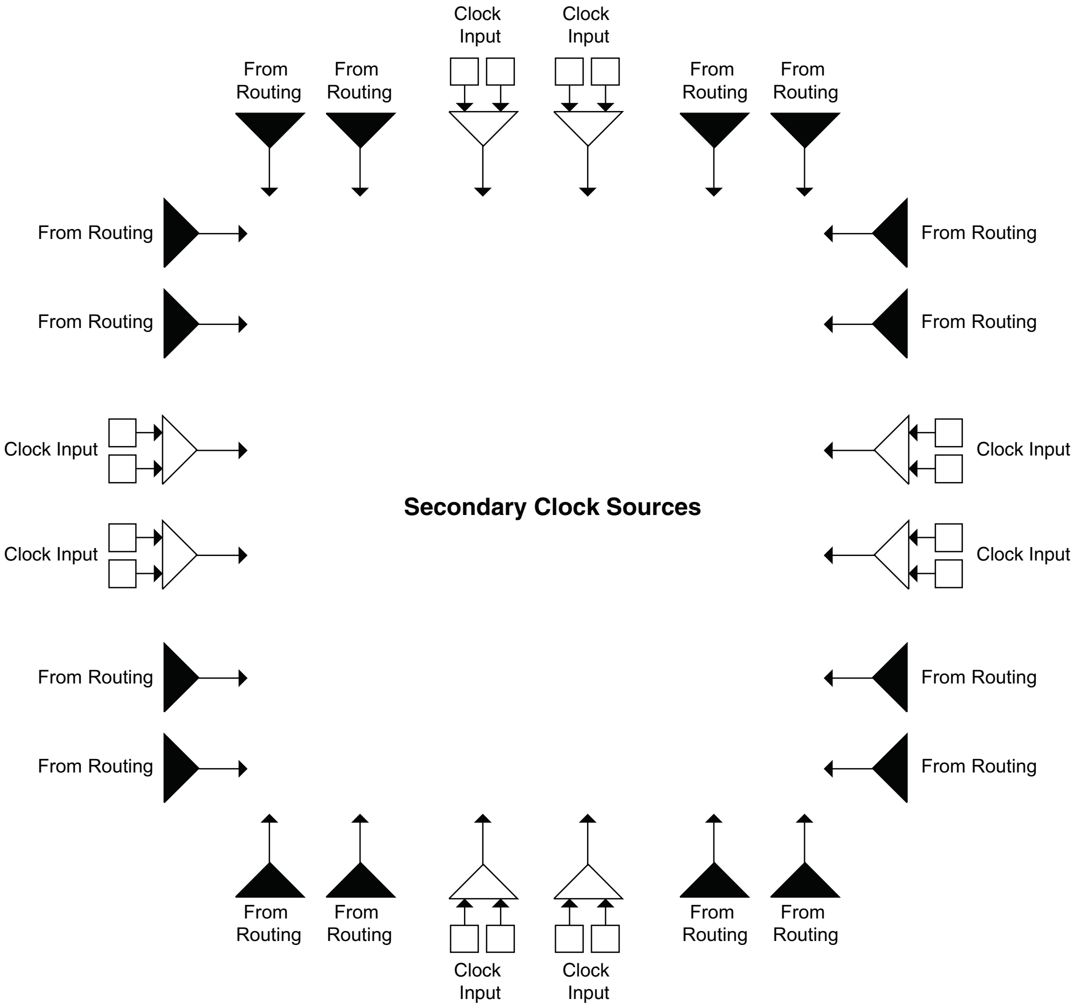
	PFU BLock		PFF Block	
Slice	Resources	Modes	Resources	Modes
Slice 0	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 1	2 LUT4s and 2 Registers	Logic, Ripple, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 2	2 LUT4s and 2 Registers	Logic, Ripple, RAM, ROM	2 LUT4s and 2 Registers	Logic, Ripple, ROM
Slice 3	2 LUT4s	Logic, ROM	2 LUT4s	Logic, ROM

Slices 0, 1 and 2 have 14 input signals: 13 signals from routing and one from the carry-chain (from the adjacent slice or PFU). There are seven outputs: six to routing and one to carry-chain (to the adjacent PFU). Slice 3 has 13 input signals from routing and four signals to routing. Table 2-2 lists the signals associated with Slice 0 to Slice 2.

Secondary Clock/Control Sources

LatticeECP2/M devices derive secondary clocks (SC0 through SC7) from eight dedicated clock input pads and the rest from routing. Figure 2-11 shows the secondary clock sources.

Figure 2-11. Secondary Clock Sources

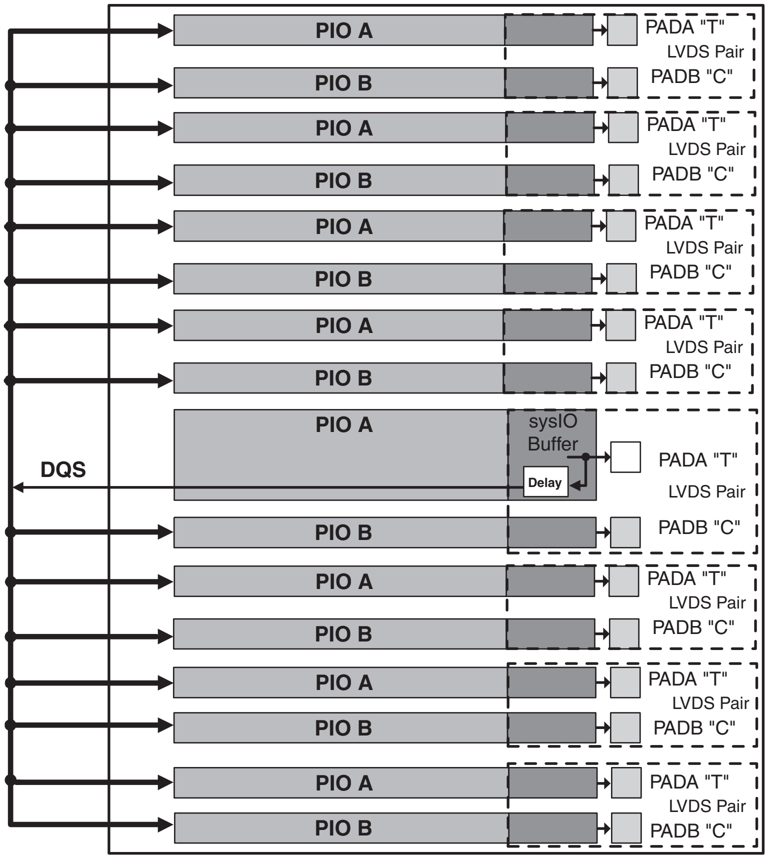


Top Edge

The PICs on the top edge are different from PIOs on the left, right and bottom edges. PIOs on this edge do not have DDR registers or DQS signals.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. Interfaces on the left and right edges are designed for DDR memories that support 16 bits of data, whereas interfaces on the bottom are designed for memories that support 18 bits of data.

Figure 2-33. DQS Input Routing for the Left and Right Edges of the Device



sets of single-ended input buffers (both ratioed and referenced). One of the referenced input buffers can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

3. **Left and Right (Banks 2, 3, 6 and 7) sysI/O Buffer Pairs (50% Differential and 100% Single-Ended Outputs)**
   The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. One of the referenced input buffers can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

   LVDS differential output drivers are available on 50% of the buffer pairs on the left and right banks.

4. **Bank 8 sysI/O Buffer Pairs (Single-Ended Outputs, Only on Shared Pins When Not Used by Configuration)**
   The sysI/O buffers in Bank 8 consist of single-ended output drivers and single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

   The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

In LatticeECP2 devices, only the I/Os on the bottom banks have programmable PCI clamps. In LatticeECP2M devices, the I/Os on the left and bottom banks have programmable PCI clamps.

Typical sysI/O I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC}, V_{CCIO8} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in LatticeECP2/M devices, see the list of additional technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Prior to and throughout programming of the FPGA, the I/O of the device have a weak-pullup resistor to V_{CCIO} on the input buffer and the output buffer is tri-stated. A pullup to V_{CCIO} is present on the input until the user programs the input differently in the FPGA design. See the DC Electrical Characteristics table of this data sheet. The pullup value will be between 20-30K ohms based on the V_{CCIO} voltage supplied on the board. This pullup will also remain active if the design does not use a particular I/O.

Supported sysI/O Standards

The LatticeECP2/M sysI/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2V, 1.5V, 1.8V, 2.5V and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individual configuration options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, MLVDS, BLVDS, LVPECL, RSDS, differential SSTL and differential HSTL. Tables 2-13 and 2-14 show the I/

Symbol	Parameter	Min.	Max.	Units
V_{CCP}[6]	PLL and Reference Clock Buffer Power	1.14	1.26	V

1. If V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. V_{CCPLL} must be connected to the same power supply as V_{CC} through careful filtering and decoupling.
2. See recommended voltages by I/O standard in subsequent table.
3. V_{CCAUX} ramp rate must not exceed 30mV/µs during power-up when transitioning between 0V and 3.3V.
4. For proper power-up configuration, users must ensure that the configuration control signals such as the CFGx, INITN, PROGRAMN and DONE pins are driven to the proper logic levels when the device powers up. The device power-up is triggered by the last of V_{CC}, V_{CCAUX} or V_{CCIO8} supplies that reaches its minimum valid levels. Alternatively, if the configuration control signals are pulled up by V_{CCIO8}, the V_{CCIO8} (configuration I/O bank) voltage must be powered up prior to or at the same time as the last of VCC or VCCAUX reaches its minimum levels.
5. For power-up, V_{CC} must reach its valid minimum value before powering up V_{CCAUX} (LatticeECP2/M “S” version devices only).
6. V_{CCRX},V_{CCTX} and V_{CCP} must be tied together in each quad and all quads need to be powered up.
7. For more power supply design recommendations, refer to TN1114 Electrical Recommendations for Lattice SERDES.

Hot Socketing Specifications[1, 2, 3, 4]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O leakage current	$0 \leq V_{IN} \leq V_{IH}$ (MAX.)	—	—	+/-1000	µA
I_{HDIN}[5]	SERDES average input current when device is powered down and inputs are driven		—	—	4	mA

1. V_{CC}, V_{CCAUX} and V_{CCIO} should rise/fall monotonically. V_{CC} and V_{CCPLL} must be connected to the same power supply (applies to ECP2-6, ECP2-12 and ECP2-20 only).
2. $0 \leq V_{CC} \leq V_{CC}$ (MAX), $0 \leq V_{CCIO} \leq V_{CCIO}$ (MAX) or $0 \leq V_{CCAUX} \leq V_{CCAUX}$ (MAX).
3. I_{DK} is additive to I_{PU}, I_{PW} or I_{BH}.
4. LVCMOS and LVTTL only.
5. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed V_{CCIB} of 1.575V, 8b10b data and internal AC coupling.

ESD Performance

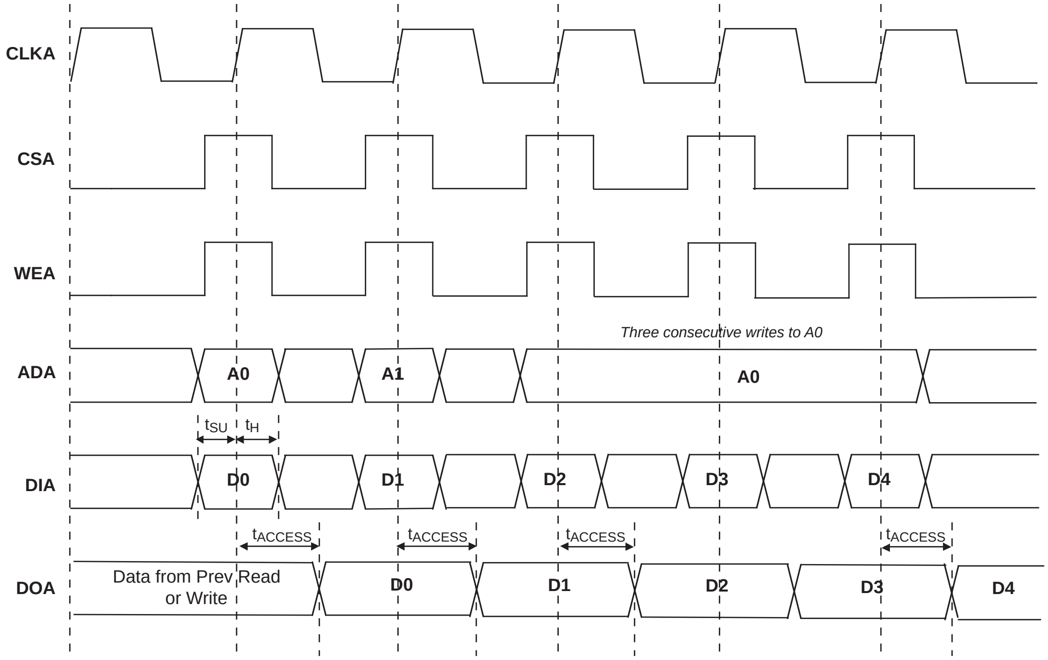
Please refer to LatticeECP2/M Product Family Qualification Summary for complete qualification data, including ESD performance.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{H_DELE}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
f_{MAX_IOE}	Clock Frequency of I/O and PFU Register	ECP2/M	—	420	—	357	—	311	MHz
General I/O Pin Parameters (using Primary Clock with PLL)[1]									
t_{COPLL}[10]	Clock to Output - PIO Output Register	LFE2-6	—	2.30	—	2.60	—	2.80	ns
		LFE2-12	—	2.30	—	2.60	—	2.80	ns
		LFE2-20	—	2.30	—	2.60	—	2.80	ns
		LFE2-35	—	2.30	—	2.60	—	2.80	ns
		LFE2-50	—	2.30	—	2.60	—	2.80	ns
		LFE2-70	—	2.30	—	2.60	—	2.80	ns
		LFE2M20	—	2.30	—	2.60	—	2.80	ns
		LFE2M35	—	2.30	—	2.60	—	2.80	ns
		LFE2M50	—	2.60	—	2.90	—	3.10	ns
		LFE2M70	—	2.60	—	2.90	—	3.10	ns
		LFE2M100	—	2.70	—	3.00	—	3.20	ns
t_{SUPLL}	Clock to Data Setup - PIO Input Register	LFE2-6	0.70	—	0.80	—	0.90	—	ns
		LFE2-12	0.70	—	0.80	—	0.90	—	ns
		LFE2-20	0.70	—	0.80	—	0.90	—	ns
		LFE2-35	0.70	—	0.80	—	0.90	—	ns
		LFE2-50	0.70	—	0.80	—	0.90	—	ns
		LFE2-70	0.70	—	0.80	—	0.90	—	ns
		LFE2M20	0.70	—	0.80	—	0.90	—	ns
		LFE2M35	0.70	—	0.80	—	0.90	—	ns
		LFE2M50	0.70	—	0.80	—	0.90	—	ns
		LFE2M70	0.70	—	0.80	—	0.90	—	ns
		LFE2M100	0.80	—	0.90	—	1.00	—	ns

Figure 3-11. Write Through (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

Table 3-9. Channel Output Jitter - x20 Mode

Description	Frequency	Min.	Typ.	Max.	Units
Deterministic	3.125 Gbps	—	0.08	0.12	UI, p-p
Random	3.125 Gbps	—	0.27	0.51	UI, p-p
Total	3.125 Gbps	—	0.35	0.59	UI, p-p
Deterministic	2.5 Gbps	—	0.09	0.19	UI, p-p
Random	2.5 Gbps	—	0.23	0.34	UI, p-p
Total	2.5 Gbps	—	0.29	0.45	UI, p-p
Deterministic	1.25 Gbps	—	0.05	0.11	UI, p-p
Random	1.25 Gbps	—	0.16	0.22	UI, p-p
Total	1.25 Gbps	—	0.20	0.28	UI, p-p

Note: Values are measured with PRBS 2^7-1, all channels operating, FPGA Logic active, I/Os around SERDES pins quiet, reference clock at x20 mode.

Table 3-10. SERDES/PCS Latency Breakdown (Parallel Clock Cycle)

Item	Description	Min.	Average	Max.	Fixed	Bypass	Units
Transmit Data Latency							
T1	FPGA Bridge Transmit[2]	1	3	5		1	word clk
T2	8b10b Encoder	—	—	—	2	1	word clk
T3	SERDES Bridge Transmit	—	—	—	2	1	word clk
T4[3]	Serializer: 8-bit mode	—	—	—	15 + Δ1	—	UI + ps
	Serializer: 10-bit mode	—	—	—	18 + Δ1	—	UI + ps
Receive Data Latency							
R1[3]	Deserializer: 8-bit mode	—	—	—	10 + Δ2	—	UI + ps
	Deserializer: 10-bit mode	—	—	—	12 + Δ2	—	UI + ps
R2	SERDES Bridge Receive	—	—	—	2	1	word clk
R3	Word Alignment	3.1	—	4	—	0	word clk
R4	8b10b Decoder	—	—	—	1	1	word clk
R5	Clock Tolerance Compensation	7	15	23		1	word clk
R6	FPGA Bridge Receive[2]	1	3	5		1	word clk

1. PCS internal parallel clock. This clock rate is the same as rxfullclk.
2. FPGA Bridge latency varies by the upsample/downsample FIFO read/write. The numbers given are for the 8b10b interface. The depth of the downsample/upsample FIFO is 4. The earliest read can be done after the write clock cycle (one clock) in downsample FIFO. The latest read will be done after the FIFO is full (4 + 1 = 5). For the 16b20b interface, the numbers are doubled: min. = 2, max. = 10. This latency depends on the internal FIFO flag operation.
3. Δ1 = -245ps, Δ2 = 700ps

Available Device Resources by Package, LatticeECP2

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA
PLL/DLL	ECP2-6	4	—	—	—
	ECP2-12	4	4	—	—
	ECP2-20	4	4	4	—
	ECP2-35	—	4	4	—
	ECP2-50	—	6	6	—
	ECP2-70	—	—	8	8

Available Device Resources by Package, LatticeECP2M

Resource	Device	256 fpBGA	484 fpBGA	672 fpBGA	900 fpBGA	1152 fpBGA
PLL/DLL	ECP2M20	10	10	—	—	—
	ECP2M35	10	10	10	—	—
	ECP2M50	—	10	10	10	—
	ECP2M70	—	—	—	10	10
	ECP2M100	—	—	—	10	10

LFE2-20E/SE Logic Signal Connections: 256 fpBGA

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C3	C3	PL2A	7	VREF2_7	T (LVDS)*
C2	C2	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO	VCCIO7	7		
-	GND	GNDIO7	7		
D3	D3	PL7A	7	LDQ8	T
D4	D4	PL6A	7	LDQ8	T (LVDS)*
D2	D2	PL7B	7	LDQ8	C
GND	GND	GNDIO7	-		
E4	E4	PL6B	7	LDQ8	C (LVDS)*
B1	B1	PL13A	7	LDQ16	T
C1	C1	PL13B	7	LDQ16	C
F5	F5	PL15A	7	LDQ16	T
VCCIO	VCC	VCCIO	7		
F4	F4	PL14A	7	LDQ16	T (LVDS)*
G6	G6	PL15B	7	LDQ16	C
G4	G4	PL14B	7	LDQ16	C (LVDS)*
D1	D1	PL16A	7	LDQS16	T (LVDS)*
GND	GND	GNDIO7	-		
E1	E1	PL16B	7	LDQ16	C (LVDS)*
F3	F3	PL17A	7	LDQ16	T
G3	G3	PL17B	7	LDQ16	C
VCCIO	VCCIO	VCCIO7	7		
F2	F2	PL18A	7	LDQ16	T (LVDS)*
F1	F1	PL18B	7	LDQ16	C (LVDS)*
GND	GND	GNDIO7	-		
G2	G2	PL19A	7	PCLKT7_0/LDQ16	T
G1	G1	PL19B	7	PCLKC7_0/LDQ16	C
H6	H6	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*
VCCIO	VCCIO	VCCIO6	6		
H5	H5	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*
H4	H4	PL22A	6	VREF2_6/LDQ25	T
GND	GND	GNDIO6	-		
H3	H3	PL22B	6	VREF1_6/LDQ25	C
H2	H2	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*
H1	H1	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*
G10	G10	VCC	-		
J4	J4	PL28A	6	LLM0_GDLLT_FB_A/LDQ25	T
J5	J5	PL28B	6	LLM0_GDLLC_FB_A/LDQ25	C
J6	J6	LLM0_PLLCAP	6		
K4	K4	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*
GND	GND	GNDIO6	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
C17	PT58B	1		C
A18	PT58A	1		T
VCCIO	VCCIO1	1		
H16	PT57B	1	PCLKC1_0	C
F16	PT57A	1	PCLKT1_0	T
K16	XRES	1		
E16	PT55B	0	PCLKC0_0	C
GND	GNDIO0	-		
G16	PT55A	0	PCLKT0_0	T
B17	PT54B	0		C
A17	PT54A	0		T
J15	PT53B	0		C
VCCIO	VCCIO0	0		
J16	PT53A	0		T
C16	PT52B	0		C
D16	PT52A	0		T
F15	PT51B	0		C
H15	PT51A	0		T
E15	PT50B	0		C
GND	GNDIO0	-		
G15	PT50A	0		T
C15	PT49B	0		C
VCCIO	VCCIO0	0		
D15	PT49A	0		T
B16	PT48B	0		C
A16	PT48A	0		T
E14	PT47B	0		C
G14	PT47A	0		T
B15	PT46B	0		C
A15	PT46A	0		T
GND	GNDIO0	-		
H14	PT45B	0		C
F14	PT45A	0		T
D14	PT44B	0		C
C14	PT44A	0		T
VCCIO	VCCIO0	0		
G13	PT43B	0		C
E13	PT43A	0		T
B14	PT42B	0		C
A14	PT42A	0		T
GND	GNDIO0	-		
H13	PT41B	0		C
F13	PT41A	0		T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
G12	PT40B	0		C
E12	PT40A	0		T
VCCIO	VCCIO0	0		
B13	PT39B	0		C
A13	PT39A	0		T
H12	PT38B	0		C
F12	PT38A	0		T
C12	PT37B	0		C
GND	GNDIO0	-		
D12	PT37A	0		T
B12	PT36B	0		C
A12	PT36A	0		T
E11	PT35B	0		C
VCCIO	VCCIO0	0		
G11	PT35A	0		T
F11	PT34B	0		C
H11	PT34A	0		T
C11	PT33B	0		C
D11	PT33A	0		T
B11	PT32B	0		C
GND	GNDIO0	-		
A11	PT32A	0		T
E10	PT31B	0		C
VCCIO	VCCIO0	0		
G10	PT31A	0		T
F10	PT30B	0		C
H10	PT30A	0		T
D10	PT29B	0		C
C10	PT29A	0		T
GND	GNDIO0	-		
VCCIO	VCCIO0	0		
A7	PT16B	0		C
B7	PT16A	0		T
A6	PT15B	0		C
B6	PT15A	0		T
C7	PT14B	0		C
GND	GNDIO0	-		
D7	PT14A	0		T
D8	PT13B	0		C
VCCIO	VCCIO0	0		
E7	PT13A	0		T
C6	PT12B	0		C
D6	PT12A	0		T

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

	LFE2M20E/SE				LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A7	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T
C6	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12		
B4	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C
B3	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12		
A4	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T
C3	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12		
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO1	1		
GNDIO	GNDIO0	-			GNDIO0	-		
VCCIO	VCCIO0	0			VCCIO0	0		
G10	VCCPLL	-			VCCPLL	-		
G7	VCC	-			VCC	-		
G9	VCC	-			VCC	-		
H7	VCC	-			VCC	-		
J10	VCC	-			VCC	-		
K10	VCC	-			VCC	-		
K8	VCC	-			VCC	-		
E7	VCCIO0	0			VCCIO0	0		
VCCIO	VCCIO0	0			VCCIO0	0		
E10	VCCIO1	1			VCCIO1	1		
VCCIO	VCCIO1	1			VCCIO1	1		
E14	VCCIO2	2			VCCIO2	2		
G12	VCCIO2	2			VCCIO2	2		
VCCIO	VCCIO2	2			VCCIO2	2		
K12	VCCIO3	3			VCCIO3	3		
M14	VCCIO3	3			VCCIO3	3		
VCCIO	VCCIO3	3			VCCIO3	3		
M10	VCCIO4	4			VCCIO4	4		
P12	VCCIO4	4			VCCIO4	4		
VCCIO	VCCIO4	4			VCCIO4	4		
M7	VCCIO5	5			VCCIO5	5		
P5	VCCIO5	5			VCCIO5	5		
VCCIO	VCCIO5	5			VCCIO5	5		
K5	VCCIO6	6			VCCIO6	6		
M3	VCCIO6	6			VCCIO6	6		
VCCIO	VCCIO6	6			VCCIO6	6		
E3	VCCIO7	7			VCCIO7	7		
G5	VCCIO7	7			VCCIO7	7		
VCCIO	VCCIO7	7			VCCIO7	7		
T15	VCCIO8	8			VCCIO8	8		
VCCIO	VCCIO8	8			VCCIO8	8		
G8	VCCAUX	-			VCCAUX	-		
H10	VCCAUX	-			VCCAUX	-		
J7	VCCAUX	-			VCCAUX	-		
K9	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A15	GND	-			GND	-		
A16	GND	-			GND	-		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
GNDIO	GNDIO7	-		
L1	PL36A	7	LDQS36	T (LVDS)*
L2	PL36B	7	LDQ36	C (LVDS)*
M7	PL37A	7	LDQ36	T
VCCIO	VCCIO7	7		
L5	PL37B	7	LDQ36	C
L3	PL38A	7	LDQ36	T (LVDS)*
L4	PL38B	7	LDQ36	C (LVDS)*
M1	PL39A	7	PCLKT7_0/LDQ36	T
GNDIO	GNDIO7	-		
M2	PL39B	7	PCLKC7_0/LDQ36	C
M6	PL41A	6	PCLKT6_0	T (LVDS)*
M5	PL41B	6	PCLKC6_0	C (LVDS)*
M3	PL42A	6	VREF2_6	T
M4	PL42B	6	VREF1_6	C
VCCIO	VCCIO6	6		
N7	PL45A	6	LLM3_SPLLT_IN_A	T (LVDS)*
GNDIO	GNDIO6	-		
N6	PL45B	6	LLM3_SPLLC_IN_A	C (LVDS)*
N1	PL46A	6	LLM3_SPLLT_FB_A	T
N2	PL46B	6	LLM3_SPLLC_FB_A	C
VCCIO	VCCIO6	6		
GNDIO	GNDIO6	-		
P6	PL52A	6	LDQS52****	T (LVDS)*
N5	PL52B	6	LDQ52	C (LVDS)*
P1	PL53A	6	LDQ52	T
VCCIO	VCCIO6	6		
P2	PL53B	6	LDQ52	C
P3	PL54A	6	LDQ52	T (LVDS)*
P4	PL54B	6	LDQ52	C (LVDS)*
P5	PL55A	6	LDQ52	T
GNDIO	GNDIO6	-		
P7	PL55B	6	LDQ52	C
VCCIO	VCCIO6	6		
GNDIO	GNDIO6	-		
R1	PL62A	6	LLM0_GPLLT_IN_A**	T (LVDS)*
GNDIO	GNDIO6	-		
R2	PL62B	6	LLM0_GPLLC_IN_A**	C (LVDS)*
R3	PL63A	6	LLM0_GPLLT_FB_A	T
R4	PL63B	6	LLM0_GPLLC_FB_A	C
VCCIO	VCCIO6	6		
R6	PL64A	6	LLM0_GDLLT_IN_A**	T (LVDS)*
R5	PL64B	6	LLM0_GDLLC_IN_A**	C (LVDS)*

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
Y6	PB8A	5	BDQ6	T
Y5	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5		
AB3	PB9A	5	BDQ6	T
AB4	PB9B	5	BDQ6	C
AB5	PB10A	5	BDQ6	T
AA6	PB10B	5	BDQ6	C
GNDIO	GNDIO5	-		
VCCIO	VCCIO5	5		
V9	PB40A	5	BDQ42	T
U9	PB40B	5	BDQ42	C
VCCIO	VCCIO5	5		
U10	PB41A	5	BDQ42	T
T10	PB41B	5	BDQ42	C
GNDIO	GNDIO5	-		
W9	PB42A	5	BDQS42****	T
Y8	PB42B	5	BDQ42	C
AA7	PB43A	5	VREF2_5/BDQ42	T
Y7	PB43B	5	VREF1_5/BDQ42	C
AB6	PB44A	5	PCLKT5_0/BDQ42	T
AB7	PB44B	5	PCLKC5_0/BDQ42	C
VCCIO	VCCIO5	5		
GNDIO	GNDIO5	-		
AA8	PB49A	4	PCLKT4_0/BDQ51	T
VCCIO	VCCIO4	4		
AB8	PB49B	4	PCLKC4_0/BDQ51	C
AA9	PB50A	4	VREF2_4/BDQ51	T
Y9	PB50B	4	VREF1_4/BDQ51	C
AB9	PB51A	4	BDQS51****	T
GNDIO	GNDIO4	-		
AB10	PB51B	4	BDQ51	C
AA10	PB52A	4	BDQ51	T
Y11	PB52B	4	BDQ51	C
VCCIO	VCCIO4	4		
GNDIO	GNDIO4	-		
V10	PB56A	4	BDQ60	T
U11	PB56B	4	BDQ60	C
V11	PB57A	4	BDQ60	T
W11	PB57B	4	BDQ60	C
AA11	PB58A	4	BDQ60	T
AB11	PB58B	4	BDQ60	C
VCCIO	VCCIO4	4		
T11	PB59A	4	BDQ60	T

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
G5	VCCIO7	7		
J8	VCCIO7	7		
K4	VCCIO7	7		
AA22	VCCIO8	8		
U19	VCCIO8	8		
H11	VCCAUX	-		
H12	VCCAUX	-		
L15	VCCAUX	-		
L8	VCCAUX	-		
M15	VCCAUX	-		
M8	VCCAUX	-		
R11	VCCAUX	-		
R12	VCCAUX	-		
A1	GND	-		
A10	GND	-		
A16	GND	-		
A22	GND	-		
AA19	GND	-		
AA4	GND	-		
AB1	GND	-		
AB22	GND	-		
B13	GND	-		
B19	GND	-		
B4	GND	-		
D16	GND	-		
D2	GND	-		
D21	GND	-		
D7	GND	-		
G19	GND	-		
G4	GND	-		
H10	GND	-		
H13	GND	-		
J14	GND	-		
J9	GND	-		
K10	GND	-		
K11	GND	-		
K12	GND	-		
K13	GND	-		
K15	GND	-		
K20	GND	-		
K3	GND	-		
K8	GND	-		
L10	GND	-		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO7	-			GNDIO7	-		
K5	PL23A	7	LDQS23	T (LVDS)*	PL27A	7	LDQS27	T*
L5	PL23B	7	LDQ23	C (LVDS)*	PL27B	7	LDQ27	C*
K4	PL24A	7	LDQ23	T	PL28A	7	LDQ27	T
VCCIO	VCCIO7	7			VCCIO7	7		
L4	PL24B	7	LDQ23	C	PL28B	7	LDQ27	C
K3	PL25A	7	LDQ23	T (LVDS)*	PL29A	7	LDQ27	T*
L3	PL25B	7	LDQ23	C (LVDS)*	PL29B	7	LDQ27	C*
J1	PL26A	7	LDQ23	T	PL30A	7	LDQ27	T
GNDIO	GNDIO7	-			GNDIO7	-		
K2	PL26B	7	LDQ23	C	PL30B	7	LDQ27	C
K1	PL28A	7	LUM1_SPLLT_IN_A/LDQ32	T (LVDS)*	PL32A	7	LUM3_SPLLT_IN_A/LDQ36	T*
L1	PL28B	7	LUM1_SPLLC_IN_A/LDQ32	C (LVDS)*	PL32B	7	LUM3_SPLLC_IN_A/LDQ36	C*
K8	PL29A	7	LUM1_SPLLT_FB_A/LDQ32	T	PL33A	7	LUM3_SPLLT_FB_A/LDQ36	T
M5	PL29B	7	LUM1_SPLLC_FB_A/LDQ32	C	PL33B	7	LUM3_SPLLC_FB_A/LDQ36	C
VCCIO	VCCIO7	7			VCCIO7	7		
M4	PL30A	7	LDQ32	T (LVDS)*	PL34A	7	LDQ36	T*
M3	PL30B	7	LDQ32	C (LVDS)*	PL34B	7	LDQ36	C*
L8	PL31A	7	LDQ32	T	PL35A	7	LDQ36	T
M6	PL31B	7	LDQ32	C	PL35B	7	LDQ36	C
GNDIO	GNDIO7	-			GNDIO7	-		
M1	PL32A	7	LDQS32	T (LVDS)*	PL36A	7	LDQS36	T*
N1	PL32B	7	LDQ32	C (LVDS)*	PL36B	7	LDQ36	C*
N3	PL33A	7	LDQ32	T	PL37A	7	LDQ36	T
VCCIO	VCCIO7	7			VCCIO7	7		
N2	PL33B	7	LDQ32	C	PL37B	7	LDQ36	C
N5	PL34A	7	LDQ32	T (LVDS)*	PL38A	7	LDQ36	T*
N4	PL34B	7	LDQ32	C (LVDS)*	PL38B	7	LDQ36	C*
M7	PL35A	7	PCLKT7_0/LDQ32	T	PL39A	7	PCLKT7_0/LDQ36	T
GNDIO	GNDIO7	-			GNDIO7	-		
M8	PL35B	7	PCLKC7_0/LDQ32	C	PL39B	7	PCLKC7_0/LDQ36	C
P3	PL37A	6	PCLKT6_0	T (LVDS)*	PL41A	6	PCLKT6_0	T*
P2	PL37B	6	PCLKC6_0	C (LVDS)*	PL41B	6	PCLKC6_0	C*
P5	PL38A	6	VREF2_6	T	PL42A	6	VREF2_6	T
N6	PL38B	6	VREF1_6	C	PL42B	6	VREF1_6	C
P4	PL39A	6		T (LVDS)*	PL43A	6		T*
VCCIO	VCCIO6	6			VCCIO6	6		
R3	PL39B	6		C (LVDS)*	PL43B	6		C*
P6	PL40A	6		T	PL44A	6		T
N7	NC	-			PL44B	6		C
P1	PL41A	6	LLM2_SPLLT_IN_A	T (LVDS)*	PL45A	6	LLM3_SPLLT_IN_A	T*
GNDIO	GNDIO6	-			GNDIO6	-		
R1	PL41B	6	LLM2_SPLLC_IN_A	C (LVDS)*	PL45B	6	LLM3_SPLLC_IN_A	C*
N8	PL42A	6	LLM2_SPLLT_FB_A	T	PL46A	6	LLM3_SPLLT_FB_A	T
R5	PL42B	6	LLM2_SPLLC_FB_A	C	PL46B	6	LLM3_SPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		
T3	PL44A	6	LDQ48	T (LVDS)*	PL48A	6	LDQ52	T*
T4	PL44B	6	LDQ48	C (LVDS)*	PL48B	6	LDQ52	C*

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ2	LLC_SQ_HDINN3	14		C
AH4	LLC_SQ_VCCTX3	14		
AK5	LLC_SQ_HDOUTP3	14		T
AK4	LLC_SQ_VCCOB3	14		
AJ5	LLC_SQ_HDOUTN3	14		C
AH5	LLC_SQ_VCCTX2	14		
AJ6	LLC_SQ_HDOUTN2	14		C
AH6	LLC_SQ_VCCOB2	14		
AK6	LLC_SQ_HDOUTP2	14		T
AH2	LLC_SQ_VCCRX2	14		
AJ3	LLC_SQ_HDINN2	14		C
AH3	LLC_SQ_VCCIB2	14		
AK3	LLC_SQ_HDINP2	14		T
AH7	LLC_SQ_VCCP	14		
AG7	LLC_SQ_REFCLKP	14		T
AF7	LLC_SQ_REFCLKN	14		C
AJ7	LLC_SQ_VCCAUX33	14		
AK11	LLC_SQ_HDINP1	14		T
AH11	LLC_SQ_VCCIB1	14		
AJ11	LLC_SQ_HDINN1	14		C
AH12	LLC_SQ_VCCRX1	14		
AK8	LLC_SQ_HDOUTP1	14		T
AH8	LLC_SQ_VCCOB1	14		
AJ8	LLC_SQ_HDOUTN1	14		C
AH9	LLC_SQ_VCCTX1	14		
AJ9	LLC_SQ_HDOUTN0	14		C
AK10	LLC_SQ_VCCOB0	14		
AK9	LLC_SQ_HDOUTP0	14		T
AH10	LLC_SQ_VCCTX0	14		
AJ12	LLC_SQ_HDINN0	14		C
AJ13	LLC_SQ_VCCIB0	14		
AK12	LLC_SQ_HDINP0	14		T
AH13	LLC_SQ_VCCRX0	14		
AF10	PB30A	5	BDQ33	T
AE8	PB30B	5	BDQ33	C
AE11	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5		
AD9	PB31B	5	BDQ33	C
AE10	PB32A	5	BDQ33	T
AD10	PB32B	5	BDQ33	C
AE13	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-		
AC12	PB33B	5	BDQ33	C

LatticeECP2/M Family Data Sheet
Ordering Information

July 2012 **Data Sheet DS1006**

LatticeECP2 Part Number Description

LFE2 – XX XE – X XXXXXX X

Device Family
ECP2 (LatticeECP2 FPGA)

Logic Capacity
6 = 6K LUTs
12 = 12K LUTs
20 = 20K LUTs
35 = 35K LUTs
50 = 50K LUTs
70 = 70K LUTs

Encryption
S = Security Series (Encryption Feature)
Blank = Standard Series (No Encryption)

Supply Voltage
E = 1.2V

Grade
C = Commercial
I = Industrial

Package
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F484 = 484-ball fpBGA
F672 = 672-ball fpBGA
F900 = 900-ball fpBGA

TN144 = 144-pin Lead-Free TQFP
QN208 = 208-pin Lead-Free PQFP
FN256 = 256-ball Lead-Free fpBGA
FN484 = 484-ball Lead-Free fpBGA
FN672 = 672-ball Lead-Free fpBGA
FN900 = 900-ball Lead-Free fpBGA

Speed
5 = Slowest
6
7 = Fastest

Ordering Information

Note:þLatticeECP2 devices are dual marked. For example, the commercial speed grade LFE2-50E-7F672C is also marked with industrial grade -6I (LFE2-50E-6F672I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

LatticeECP2 Standard Series Devices, Lead-Free Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5TN144C	90	1.2V	-5	Lead-Free TQFP	144	COM	6
LFE2-6E-6TN144C	90	1.2V	-6	Lead-Free TQFP	144	COM	6
LFE2-6E-7TN144C	90	1.2V	-7	Lead-Free TQFP	144	COM	6
LFE2-6E-5FN256C	190	1.2V	-5	Lead-Free fpBGA	256	COM	6
LFE2-6E-6FN256C	190	1.2V	-6	Lead-Free fpBGA	256	COM	6
LFE2-6E-7FN256C	190	1.2V	-7	Lead-Free fpBGA	256	COM	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5TN144C	93	1.2V	-5	Lead-Free TQFP	144	COM	12
LFE2-12E-6TN144C	93	1.2V	-6	Lead-Free TQFP	144	COM	12
LFE2-12E-7TN144C	93	1.2V	-7	Lead-Free TQFP	144	COM	12
LFE2-12E-5QN208C	131	1.2V	-5	Lead-Free PQFP	208	COM	12
LFE2-12E-6QN208C	131	1.2V	-6	Lead-Free PQFP	208	COM	12
LFE2-12E-7QN208C	131	1.2V	-7	Lead-Free PQFP	208	COM	12
LFE2-12E-5FN256C	193	1.2V	-5	Lead-Free fpBGA	256	COM	12
LFE2-12E-6FN256C	193	1.2V	-6	Lead-Free fpBGA	256	COM	12
LFE2-12E-7FN256C	193	1.2V	-7	Lead-Free fpBGA	256	COM	12
LFE2-12E-5FN484C	297	1.2V	-5	Lead-Free fpBGA	484	COM	12
LFE2-12E-6FN484C	297	1.2V	-6	Lead-Free fpBGA	484	COM	12
LFE2-12E-7FN484C	297	1.2V	-7	Lead-Free fpBGA	484	COM	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5QN208C	131	1.2V	-5	Lead-Free PQFP	208	COM	20
LFE2-20E-6QN208C	131	1.2V	-6	Lead-Free PQFP	208	COM	20
LFE2-20E-7QN208C	131	1.2V	-7	Lead-Free PQFP	208	COM	20
LFE2-20E-5FN256C	193	1.2V	-5	Lead-Free fpBGA	256	COM	20
LFE2-20E-6FN256C	193	1.2V	-6	Lead-Free fpBGA	256	COM	20
LFE2-20E-7FN256C	193	1.2V	-7	Lead-Free fpBGA	256	COM	20
LFE2-20E-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	COM	20
LFE2-20E-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	COM	20
LFE2-20E-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	COM	20
LFE2-20E-5FN672C	402	1.2V	-5	Lead-Free fpBGA	672	COM	20
LFE2-20E-6FN672C	402	1.2V	-6	Lead-Free fpBGA	672	COM	20
LFE2-20E-7FN672C	402	1.2V	-7	Lead-Free fpBGA	672	COM	20